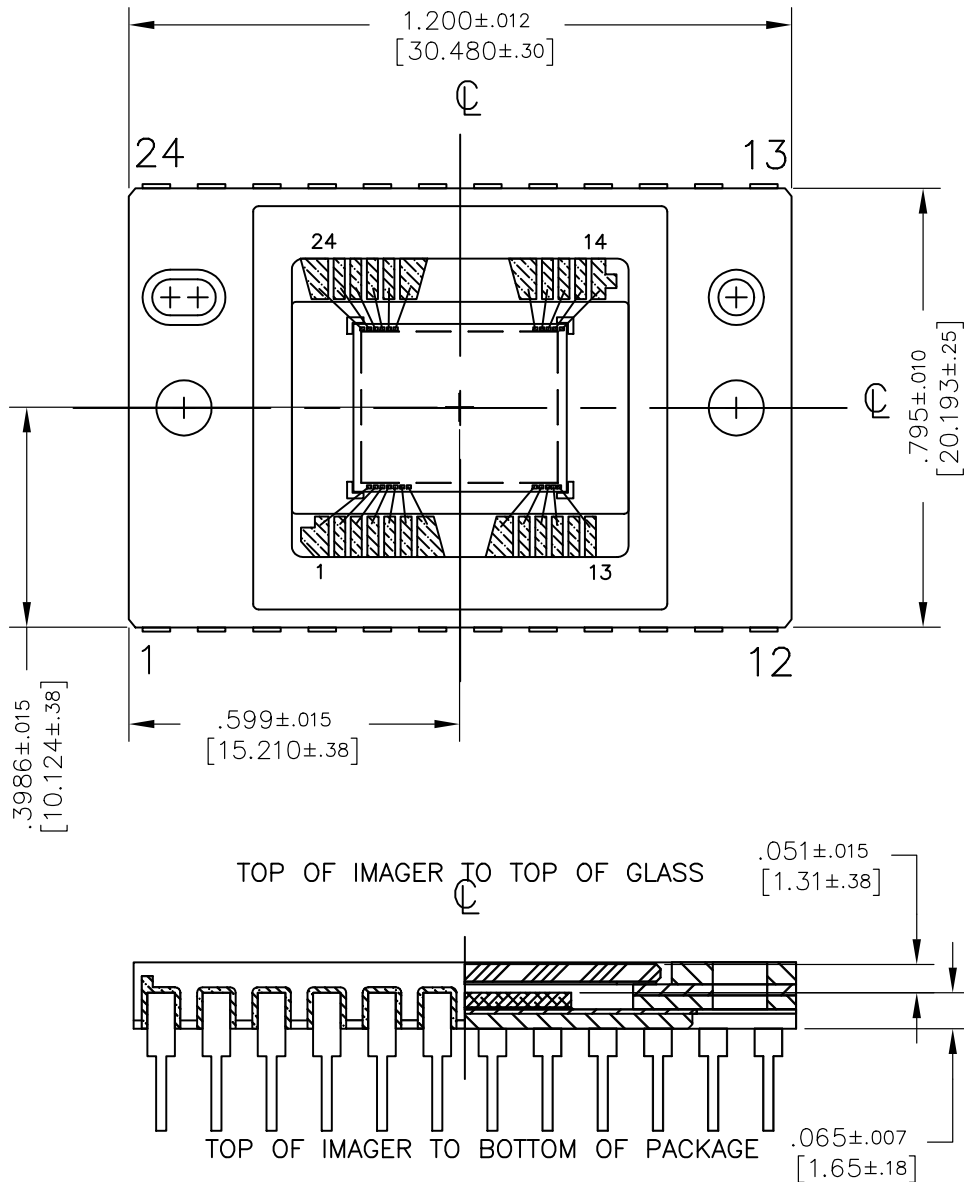


CERAMIC DIP 24, 30.48x20.19
CASE 125AW
ISSUE O

DATE 30 JUL 2014




NOTES:

- CENTER OF IMAGE IS OFFSET FROM CENTER OF PACKAGE BY (-.030, .028)mm NOMINAL.
- DIE IS ALIGNED WITHIN +/- 2 DEGREE OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

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DESCRIPTION:	CERAMIC DIP 24, 30.48x20.19	PAGE 2 OF 2

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